

# Summary

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SEMI Workshop on e-manufacturing & APC/FDC— Giichi Inoue — Slide 1

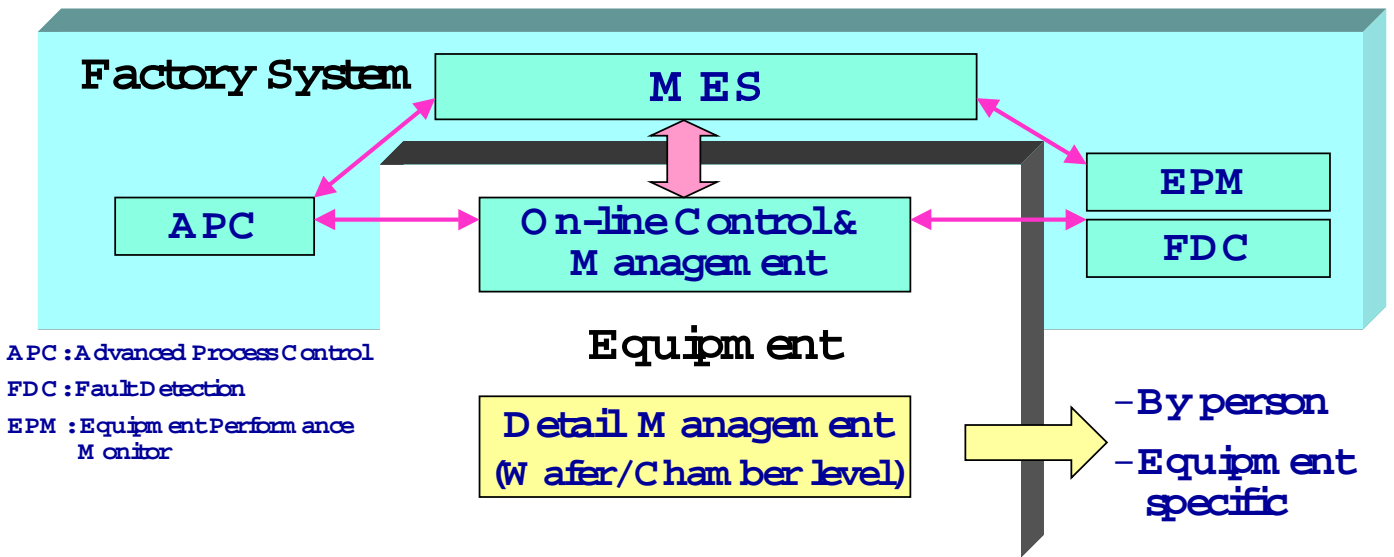
## Requirement for Equipment

- **300mm**
    - High equipment cost
    - Fully automated factory operation
  - **Larger wafer + Finer process**
    - Wafer level control
    - Module level management
    - Reduction of process deviation and individual equipment differences in performance..
- } **Higher run rate**  
} **Higher reliability**
- } **High level process control and management**
- Base for APC**
- ➔ **Heavier load for equipment management and control in 300mm fab. (for both users and suppliers)**



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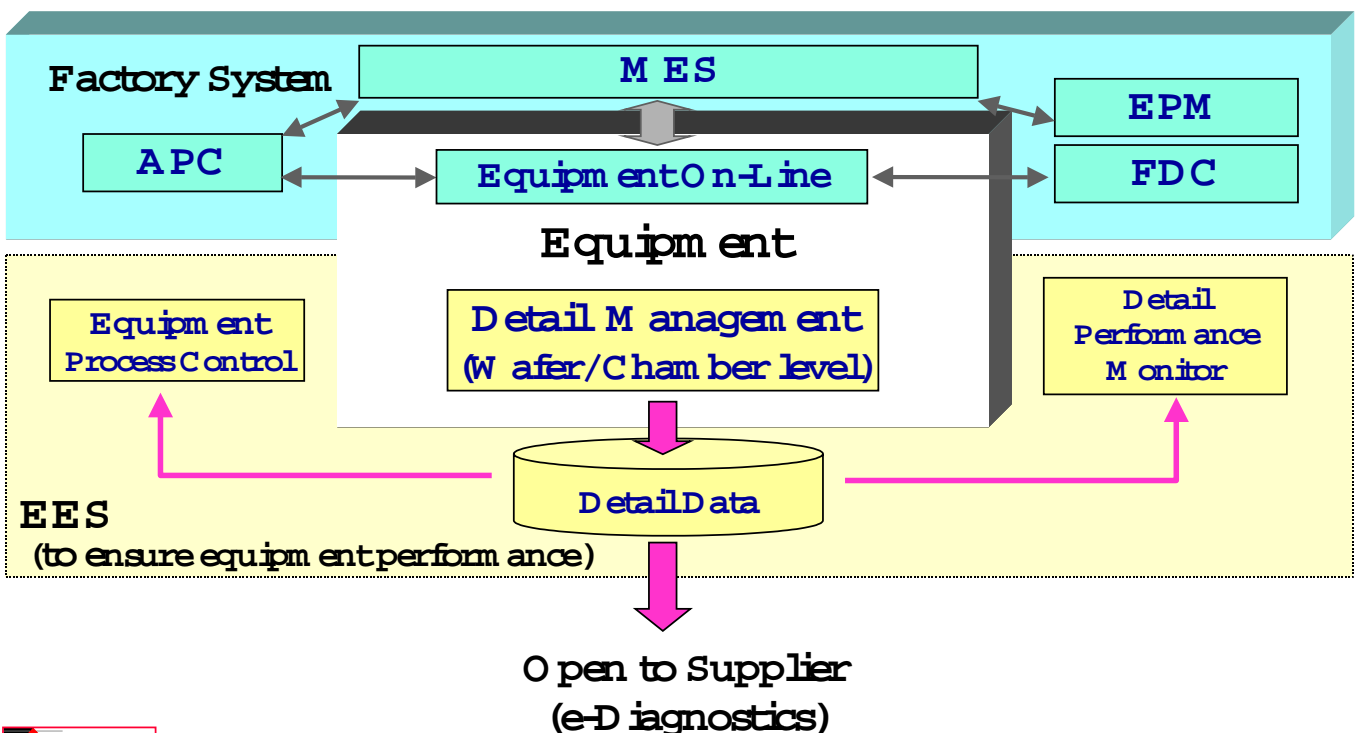
# Current Level



- Factory system focuses on lot/ equipment level management
- Weaker system support for detail equipment management.



# Position of EES



# EES Items

- **Infrastructure/ System Base**
    - **Detail data collection from equipment**
    - **Open network (to suppliers) and security**
  - **System Structure**
    - **Position of EES, relation to factory system (APC, Equipment Maintenance, etc.)**
  - **Services**
    - **New services (e-Diagnostics, etc.)**
    - **Partition of roles and responsibilities**
- }
 

**System Aspect**

**Business Model based on IT**



# Next Step

- **System Base/ Infrastructure... Start from current situation**
  - **System Structure/ Business Model... Based on future prospect**
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- **Guidelines ... To show future prospect and direction**
  - **Framework ... To show system structure and partition**
- ↓
- **Joint discussion and study by device makers and suppliers to define expected roles**

